

The 21<sup>st</sup> Korean Conference on Semiconductors  
**제21회 한국반도체학술대회**  
February 24–26, 2014 / Hanyang University, Seoul, Korea

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A. Interconnect & Package 분과

**[WC2-A] 3D & 2.5D Packaging Technology**

<b>Date</b>	Feb. 26, 2014 (Wed.)
<b>Place</b>	Room C / 제1공학관 401호 (# 401, Engineering Building I)

Session Chair: 이후정 교수(성균관대학교),

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- WC2-A-1**    13:05-13:20    **TSV Bumping 공정을 위한 저온 Nitride & Oxide 필름 개발 및 특성 연구 (Study on the Characteristics of Low Temperature Chemical Vapor Deposited Silicon Nitride and Silicon Oxide Film in Through Silicon via Bumping Process)**  
저자: 양주현, 최동진, 정래형, 김진평, 이웅선, 서민석, 변광유  
소속: Advanced PKG Development Team, SK hynix Inc.
- WC2-A-2**    13:20-13:35    **Electrical Resistance Evolution of Cu Electroplated on a Si Interposer**  
저자: Wan-Gyu Lee  
소속: Department of Nanodevice, National NanoFab Center
- WC2-A-3**    13:35-13:50    **Through-Silicon-Via(TSV) Filling by Electrochemical Deposition with High Frequency Pulsed-Current**  
저자: Sanghyun Jin<sup>1</sup>, Geon Wang<sup>1</sup>, Sungho Seo<sup>2</sup>, and Bongyong Yoo<sup>1,2</sup>  
소속: <sup>1</sup>Department of Materials Engineering, Hanyang University, <sup>2</sup>Department of Bionanotechnology, Hanyang University
- WC2-A-4**    13:50-14:05    **Effect of Design on Thermo-Mechanical Stress in Through-Silicon Via**  
저자: Joo-Sun Hwang and Won-Jun Lee  
소속: Faculty of Nanotechnology and Advanced Materials Engineering, Sejong University
- WC2-A-5**    14:05-14:20    **Solder Thickness Effect on the Interfacial Reaction Characteristics of Cu/Sn-3.5Ag Micro-Bump for 3D Integration**  
저자: Byeong-rok Lee<sup>1</sup>, Young-ki Ko<sup>2</sup>, Chang-woo Lee<sup>2</sup>, and Young-bae Park<sup>1</sup>  
소속: <sup>1</sup>School of Materials Science and Engineering, Andong National University, <sup>2</sup>Micro-Joining Center, Korea Institute of Industrial Technology